IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					rials and Mfg Information			
upplier	r Information														
Company name*			Company unique ID			Į	Unique ID Authority					Response Date*			
onsemi												2024-05-18			
ontact Na	ame		Title - Contact			I	Phone - Contact*					Email - Contact*			
Product-E	Env-Stewards		Product Enviro Compliance]	NA					Product-Env-Stewards@onsemi.com			
uthorized	d Representative*	Title - Representative			I	Phone - Representative*					Email - Representative*				
roduct-E	Env-Stewards	Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr It		em Number Mfr Item Name				Effective Date	Date Version Manufacturing Site		Site	We	ght*	UOM	Unit Type	
		TIP29CG BIP T0220 NPN 1		A 100V		2024-05-18 CN5			196	2.01	mg	Each			
	cturing Process Informa		Terminal Base	Alloy	-STD-020 MS	I Pating	Dank Proc	ass Rody	Tamparati	nre Max Time	at Daak T	Tamparatura	Numbe	er of Reflow Cyc	Jac
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omments			CO Alloy		113					130		Isccolius	13		
omments	·														
or more i	information regarding materia	l composition	nlease refer to	n nage 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Priective 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55 mg		Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.98	mg	A	Lead (Pb)	7439-92-1	7a	78.831	mg
			Supplier	Tin (Sn)	7440-31-5		4.149	mg
Lead Frame	1300.04	mg	Supplier	Copper (Cu)	7440-50-8		1300.04	mg
Mold Compound-Black	543.9			Brominated epoxy resin	proprietary data		10.878	mg
			Supplier	Phenolic Resin	Proprietary Data		27.195	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		16.317	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		435.12	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		54.39	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Al	0.41	mg	Supplier	Aluminum (Al)	7429-90-5		0.41	mg